Estimating Power Consumption on the TMS320C5517 Digital Signal Processor

ABSTRACT

This article discusses the power consumption of the Texas Instruments TMS320C5517. Power consumption on these devices is highly application-dependent. The low-core voltage and other power design optimizations allow these devices to operate with industry-leading performance, while maintaining a low power-to-performance ratio.

The power data presented in this article are based on measured data with TMS320C5517 silicon revision 2.1 or earlier devices.

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## Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

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<td>April 2014</td>
<td>*</td>
<td>Initial Release</td>
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